

# TPH2R608NH

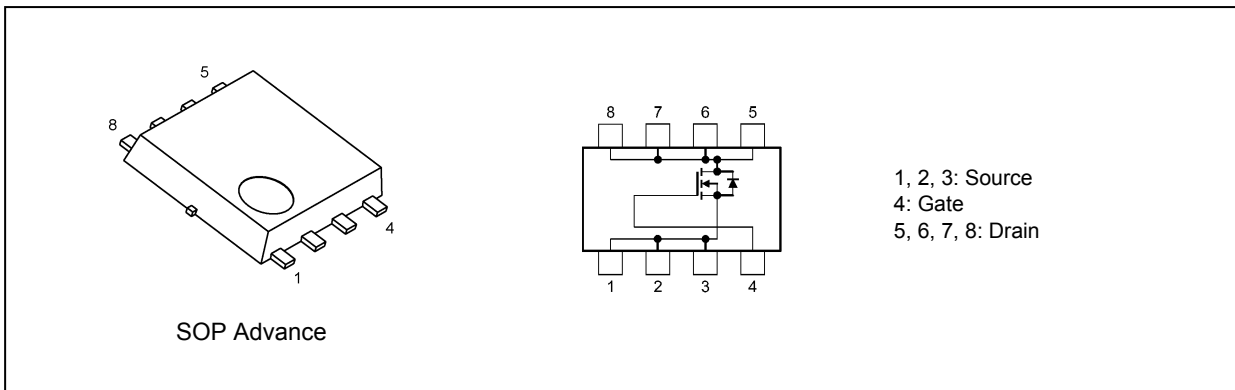
## 1. Applications

- High-Efficiency DC-DC Converters
- Switching Voltage Regulators

## 2. Features

- (1) High-speed switching
- (2) Small gate charge:  $Q_{SW} = 28 \text{ nC}$  (typ.)
- (3) Low drain-source on-resistance:  $R_{DS(ON)} = 2.1 \text{ m}\Omega$  (typ.) ( $V_{GS} = 10 \text{ V}$ )
- (4) Low leakage current:  $I_{DSS} = 10 \text{ }\mu\text{A}$  (max) ( $V_{DS} = 75 \text{ V}$ )
- (5) Enhancement mode:  $V_{th} = 2.0 \text{ to } 4.0 \text{ V}$  ( $V_{DS} = 10 \text{ V}$ ,  $I_D = 1.0 \text{ mA}$ )

## 3. Packaging and Internal Circuit



## 4. Absolute Maximum Ratings (Note) ( $T_a = 25 \text{ }^\circ\text{C}$ unless otherwise specified)

| Characteristics   | Symbol    | Rating     | Unit             |
|---|-----------|------------|------------------|
| Drain-source voltage  | $V_{DSS}$ | 75         | V                |
| Gate-source voltage   | $V_{GSS}$ | $\pm 20$   |                  |
| Drain current (DC) (Note 1)                                       | $I_D$     | 150        | A                |
| Drain current (DC) (Silicon limit) (Note 1), (Note 2)             | $I_D$     | 168        | A                |
| Drain current (pulsed) ( $t = 100 \text{ }\mu\text{s}$ ) (Note 1) | $I_{DP}$  | 500        | A                |
| Power dissipation ( $T_c = 25 \text{ }^\circ\text{C}$ )           | $P_D$     | 142        | W                |
| Power dissipation (Note 3)  | $P_D$     | 2.5        | W                |
| Power dissipation (Note 4)  | $P_D$     | 0.8        | W                |
| Single-pulse avalanche energy (Note 5)                            | $E_{AS}$  | 149        | mJ               |
| Single-pulse avalanche current (Note 5)                           | $I_{AS}$  | 120        | A                |
| Channel temperature   | $T_{ch}$  | 150        | $^\circ\text{C}$ |
| Storage temperature   | $T_{stg}$ | -55 to 150 | $^\circ\text{C}$ |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Start of commercial production

2015-01

**5. Thermal Characteristics**

| Characteristics   | Symbol         | Max  | Unit               |
|---|----------------|------|--------------------|
| Channel-to-case thermal resistance ( $T_c = 25\text{ }^\circ\text{C}$ )             | $R_{th(ch-c)}$ | 0.88 | $^\circ\text{C/W}$ |
| Channel-to-ambient thermal resistance ( $T_a = 25\text{ }^\circ\text{C}$ ) (Note 3) | $R_{th(ch-a)}$ | 50   |                    |
| Channel-to-ambient thermal resistance ( $T_a = 25\text{ }^\circ\text{C}$ ) (Note 4) | $R_{th(ch-a)}$ | 156  |                    |

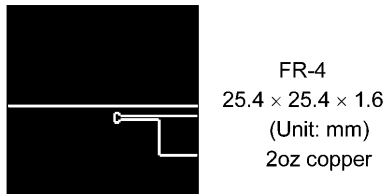
Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: Limited by package limit. Silicon chip capability is 168 A. ( $T_c = 25\text{ }^\circ\text{C}$ )

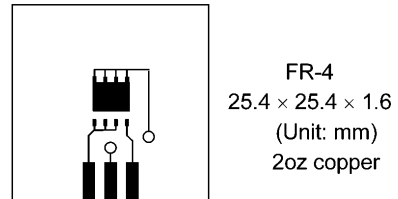
Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 5:  $V_{DD} = 60\text{ V}$ ,  $T_{ch} = 25\text{ }^\circ\text{C}$  (initial),  $L = 0.008\text{ mH}$ ,  $I_{AS} = 120\text{ A}$



**Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)**



**Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)**

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

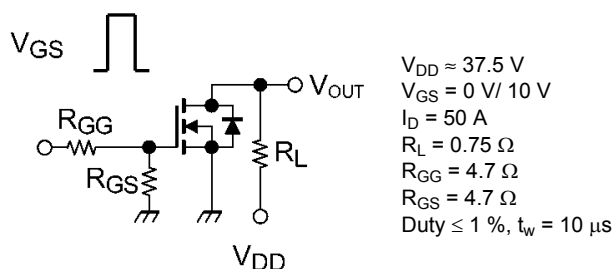
**6. Electrical Characteristics**

**6.1. Static Characteristics ( $T_a = 25\text{ }^\circ\text{C}$  unless otherwise specified)**

| Characteristics                | Symbol        | Test Condition                                  | Min | Typ. | Max       | Unit             |
|--------------------------------|---------------|---|-----|------|-----------|------------------|
| Gate leakage current           | $I_{GSS}$     | $V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$ | —   | —    | $\pm 0.1$ | $\mu\text{A}$    |
| Drain cut-off current          | $I_{DSS}$     | $V_{DS} = 75\text{ V}, V_{GS} = 0\text{ V}$     | —   | —    | 10        |                  |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $I_D = 10\text{ mA}, V_{GS} = 0\text{ V}$       | 75  | —    | —         | V                |
|                                | $V_{(BR)DSX}$ | $I_D = 10\text{ mA}, V_{GS} = -20\text{ V}$     | 55  | —    | —         |                  |
| Gate threshold voltage         | $V_{th}$      | $V_{DS} = 10\text{ V}, I_D = 1.0\text{ mA}$     | 2.0 | —    | 4.0       |                  |
| Drain-source on-resistance     | $R_{DS(ON)}$  | $V_{GS} = 10\text{ V}, I_D = 50\text{ A}$       | —   | 2.1  | 2.6       | $\text{m}\Omega$ |

**6.2. Dynamic Characteristics ( $T_a = 25\text{ }^\circ\text{C}$  unless otherwise specified)**

| Characteristics                | Symbol     | Test Condition  | Min | Typ. | Max  | Unit          |
|--------------------------------|------------|---|-----|------|------|---------------|
| Input capacitance              | $C_{iss}$  | $V_{DS} = 37.5\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$ | —   | 4600 | 6000 | $\mu\text{F}$ |
| Reverse transfer capacitance   | $C_{riss}$ |   | —   | 50   | 95   |               |
| Output capacitance             | $C_{oss}$  |   | —   | 1100 | —    |               |
| Gate resistance                | $r_g$      | —   | —   | 1.0  | 1.5  | $\Omega$      |
| Switching time (rise time)     | $t_r$      | See Fig. 6.2.1  | —   | 11   | —    | ns            |
| Switching time (turn-on time)  | $t_{on}$   |   | —   | 30   | —    |               |
| Switching time (fall time)     | $t_f$      |   | —   | 15   | —    |               |
| Switching time (turn-off time) | $t_{off}$  |   | —   | 56   | —    |               |



**Fig. 6.2.1 Switching Time Test Circuit**

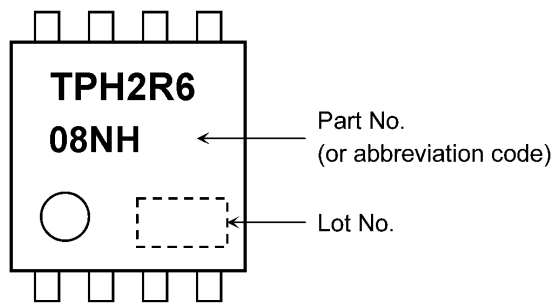
**6.3. Gate Charge Characteristics ( $T_a = 25\text{ }^\circ\text{C}$  unless otherwise specified)**

| Characteristics                                 | Symbol    | Test Condition  | Min | Typ. | Max | Unit |
|---|-----------|---|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | $Q_g$     | $V_{DD} \approx 37.5\text{ V}, V_{GS} = 10\text{ V}, I_D = 50\text{ A}$ | —   | 72   | —   | nC   |
| Gate-source charge 1                            | $Q_{gs1}$ |   | —   | 24   | —   |      |
| Gate-drain charge                               | $Q_{gd}$  |   | —   | 18   | —   |      |
| Gate switch charge                              | $Q_{sw}$  |   | —   | 28   | —   |      |

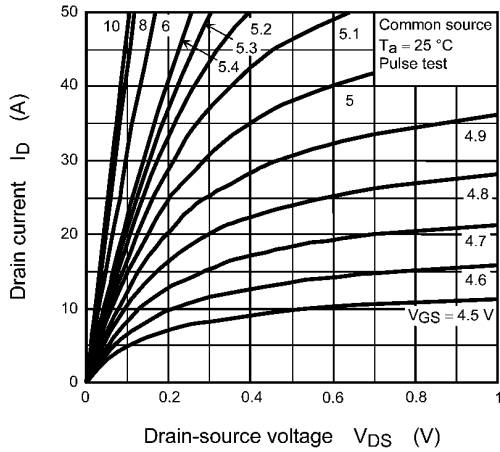
**6.4. Source-Drain Characteristics ( $T_a = 25\text{ }^\circ\text{C}$  unless otherwise specified)**

| Characteristics                         | Symbol  | Test Condition                               | Min | Typ. | Max  | Unit |
|---|---|--|-----|------|------|------|
| Reverse drain current (pulsed) (Note 6) | $I_{DRP}$<br>( $t = 100\text{ }\mu\text{s}$ ) | —  | —   | —    | 500  | A    |
| Diode forward voltage                   | $V_{DSF}$                                     | $I_{DR} = 150\text{ A}, V_{GS} = 0\text{ V}$ | —   | —    | -1.2 | V    |

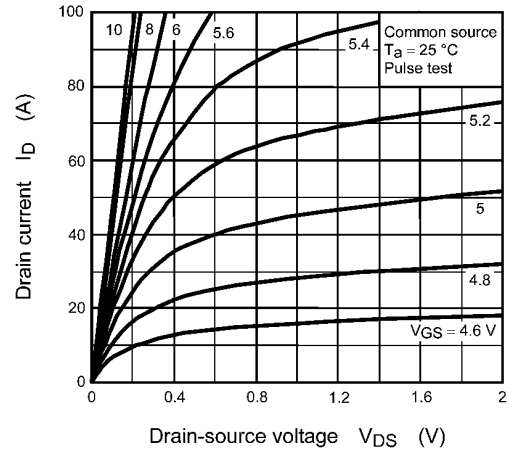
Note 6: Ensure that the channel temperature does not exceed  $150\text{ }^\circ\text{C}$ .

**7. Marking****Fig. 7.1 Marking**

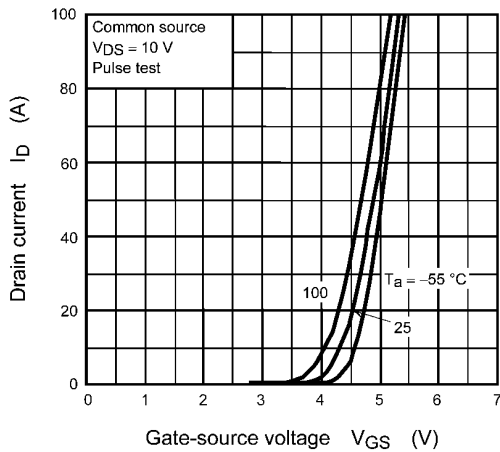
**8. Characteristics Curves (Note)**



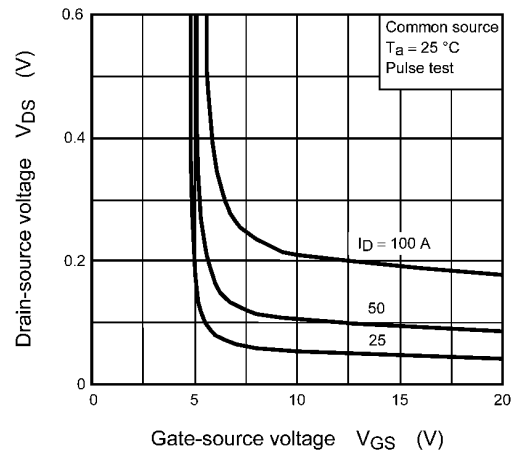
**Fig. 8.1  $I_D - V_{DS}$**



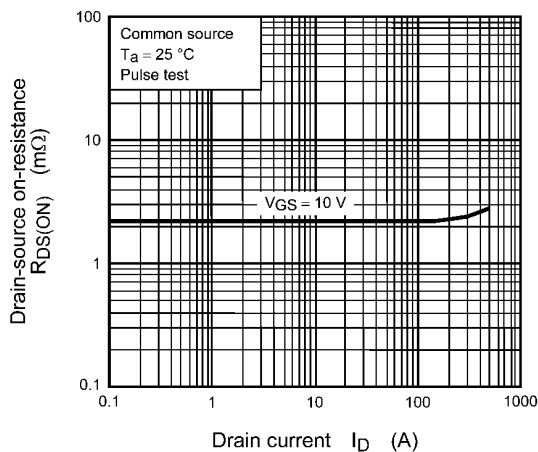
**Fig. 8.2  $I_D - V_{DS}$**



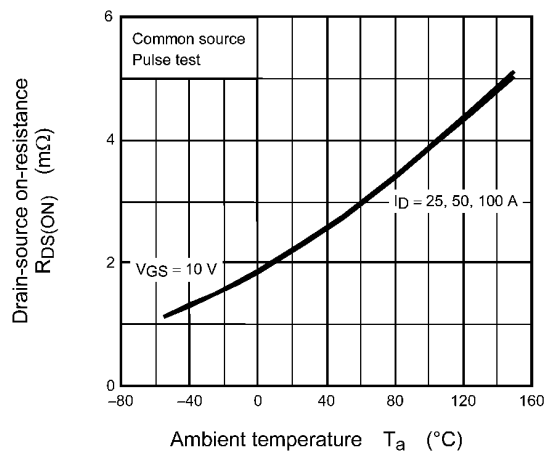
**Fig. 8.3  $I_D - V_{GS}$**



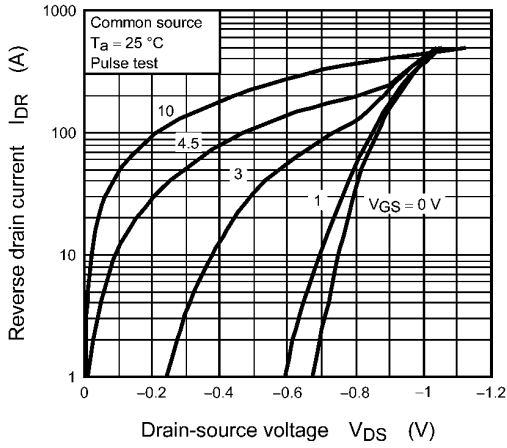
**Fig. 8.4  $V_{DS} - V_{GS}$**



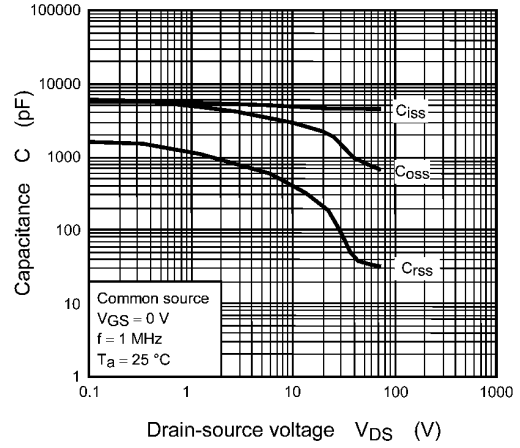
**Fig. 8.5  $R_{DS(ON)} - I_D$**



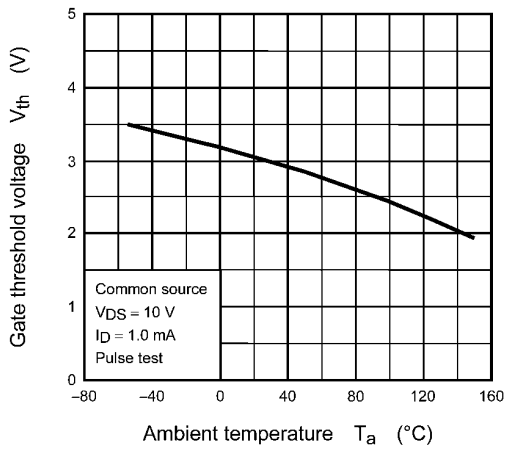
**Fig. 8.6  $R_{DS(ON)} - T_a$**



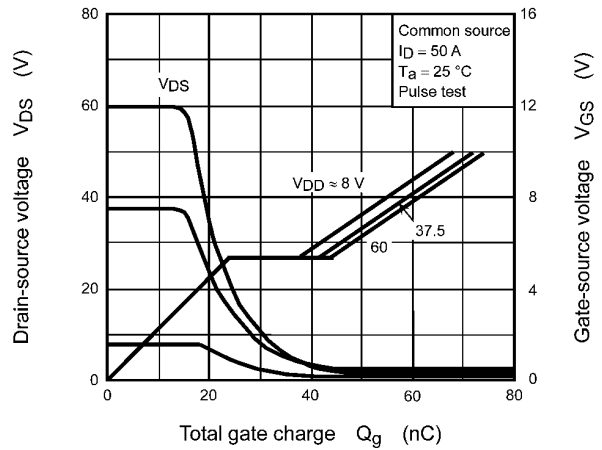
**Fig. 8.7  $I_{DR} - V_{DS}$**



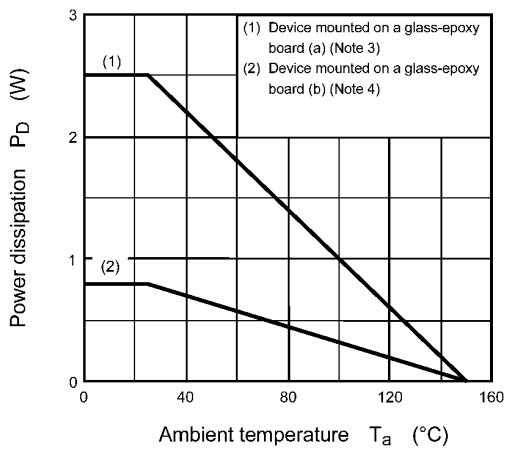
**Fig. 8.8 Capacitance -  $V_{DS}$**



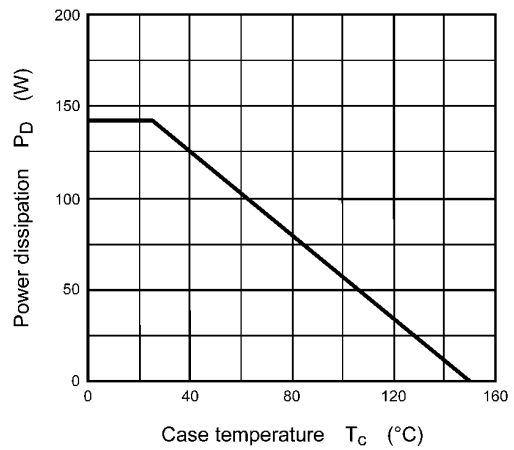
**Fig. 8.9  $V_{th} - T_a$**



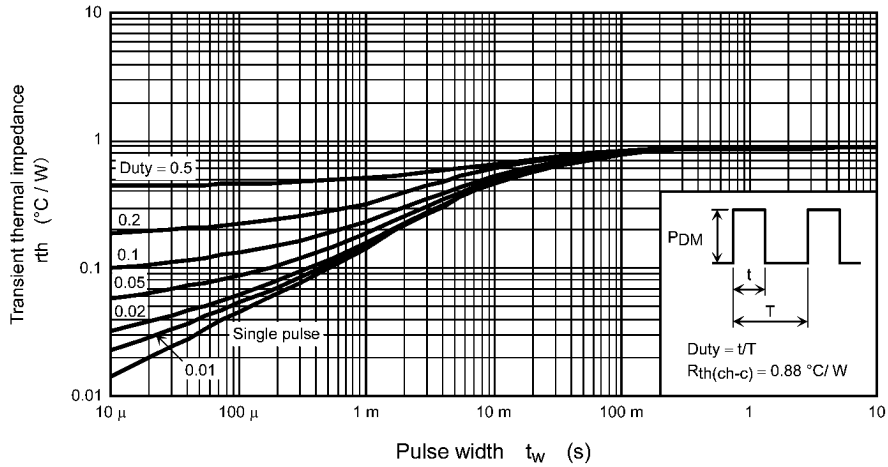
**Fig. 8.10 Dynamic Input/Output Characteristics**



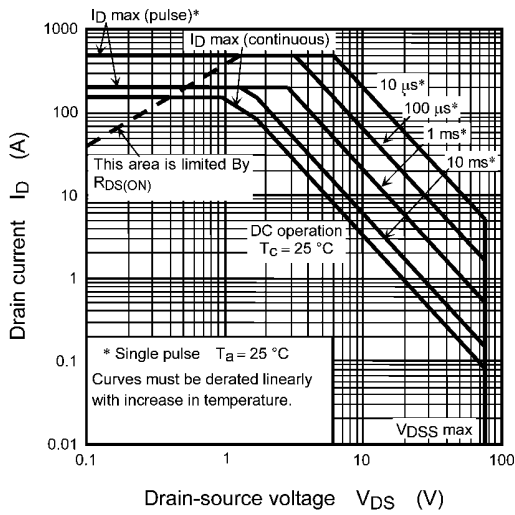
**Fig. 8.11  $P_D - T_a$   
(Guaranteed Maximum)**



**Fig. 8.12  $P_D - T_c$   
(Guaranteed Maximum)**



**Fig. 8.13  $r_{th} - t_w$**   
(Guaranteed Maximum)

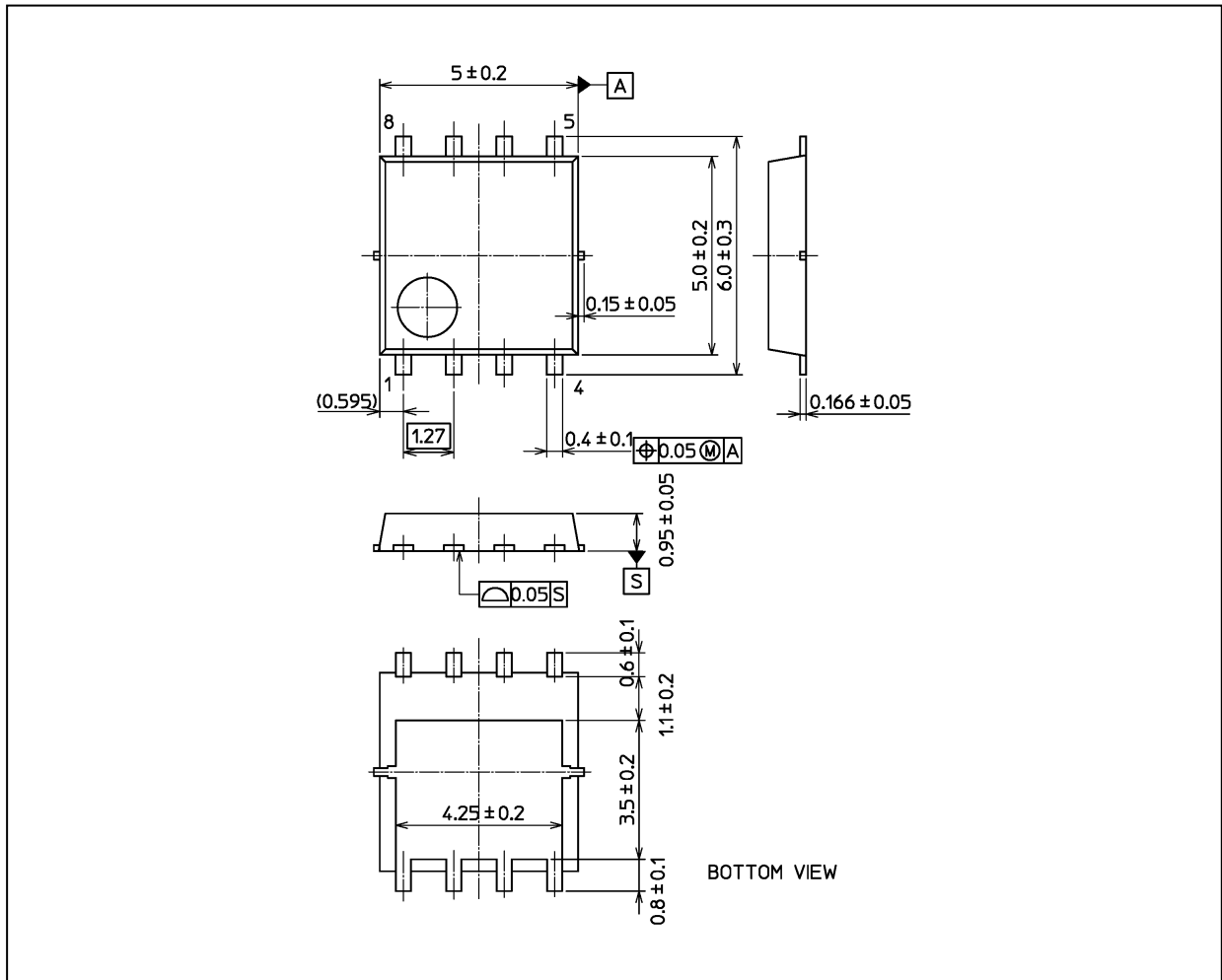


**Fig. 8.14 Safe Operating Area**  
(Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

**Package Dimensions**

Unit: mm



Weight: 0.069 g (typ.)

| Package Name(s)       |
|-----------------------|
| TOSHIBA: 2-5Q1S       |
| Nickname: SOP Advance |



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